

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions and listings of claims in the application:

1. (Currently amended) A method for manufacturing a relief material for seamless printing using a liquid-state photosensitive resin, the method comprising:

~~a setting step of~~ setting a workpiece using either of a printing cylinder ~~[[and]]~~ or a printing sleeve, which is integrally supported by a metallic mandrel, to a holding and rotating ~~means~~ device for holding and rotating the workpiece;

~~a supplying step of~~ supplying a liquid-state photosensitive resin having a viscosity ~~capable of holding~~ that retains an ~~applying~~ applied shape without being influenced by ~~[[the]]~~ gravity ~~[[and]]~~ or centrifugal force due to rotation, to a resin receiving plate which has ~~a predetermined~~ an angle of inclination and ~~of which~~ whose front end has a doctor blade shape ~~[[by]]~~ from a resin supplying ~~means at a desired~~ applied width device in a linear mode by linearly moving the resin supplying device in an axial direction of the workpiece;

~~a molding step of molding~~ applying the liquid-state photosensitive resin supplied to the resin receiving plate ~~into a predetermined~~ to an outer periphery of the workpiece at an applied thickness ~~[[by a]]~~ with the front-end cutting edge of the resin receiving plate while rotating the workpiece ~~and applying the resin to the outer periphery of the workpiece at a desired applied width;~~ and

~~[[an]]~~ exposing step of forming a photosensitive resin-cured layer by applying high-intensity ultraviolet light to the liquid-state photosensitive resin applied to the outer periphery of the workpiece while rotating the workpiece ~~and thereby~~ to form a

photosensitive resin cured layer by optically curing the liquid-state photosensitive resin so that it can be carved by an infrared laser beam.

2. (Currently amended) The method ~~for manufacturing a relief material for seamless printing~~ according to claim 1, ~~characterized in that~~ wherein at least one end of the resin receiving plate has a resin flow preventive movable dam linearly movable in the ~~axis center~~ axial direction of the workpiece.

3. (Currently amended) The method ~~for manufacturing a relief material for seamless printing~~ according to claim 1, further comprising ~~a shaping step of~~ shaping the surface of the photosensitive resin cured layer.

4. (Currently amended) The method ~~for manufacturing a relief material for seamless printing~~ according to claim 1, ~~characterized in that~~ wherein the viscosity of the liquid-state photosensitive resin supplied ~~in the supplying step~~ ranges from ~~between~~ 6 ~~[[and]]~~ to 50kPa · s ~~(both included)~~ at 20°C and the ultraviolet light in the exposing step has a wavelength area of from 200 to 400 nm and an ultraviolet intensity of 10mW/ cm² or more.

5. (Currently amended) The method ~~for manufacturing a relief material for seamless printing~~ according to ~~any one of claims~~ claim 1 ~~[[to 4]]~~, ~~characterized in that by linearly moving the resin supplying means in the axis center direction of the workpiece~~ wherein in the supplying step, ~~either of first supply for supplying the liquid-state photosensitive resin housed in a resin vessel to the resin receiving plate in the linear mode and a second supply for supplying liquid state photosensitive resin is~~ supplied to the resin receiving plate from at least one or more resin supplying nozzles of the resin supplying ~~means provided for the desired applied width is performed~~ device.

6. (Currently amended) The method ~~for manufacturing a relief material for seamless printing~~ according to ~~any one of claims~~ claim 1 ~~[[to 5]]~~, characterized by ~~applying~~ wherein the liquid-state photosensitive resin is applied to the outer periphery of the workpiece at a desired thickness while gradually expanding ~~[[the]]~~ a gap between the front-end ~~cutting edge~~ of the resin receiving plate and the outer periphery of the workpiece by moving the resin receiving plate vertically relative to the axis ~~center~~ of the workpiece in the ~~molding~~ applying step.

7. (Currently amended) The method ~~for manufacturing a relief material for seamless printing~~ according to ~~any one of claim~~ 1 ~~[[to 6]]~~, characterized by ~~performing the treatment in~~ wherein the supplying step is performed a plurality of times.

8. (Currently amended) The method ~~for manufacturing a relief material for seamless printing~~ according to ~~any one of claims~~ claim 1 ~~[[to 7]]~~, further comprising a first removing step for removing extra cured photosensitive resin from the cured layer ~~optically cured by exceeding~~ that exceeds a desired width in the exposing step to a desired thickness in parallel with or after ~~[[the]]~~ a shaping step.

9. (Currently amended) The method ~~for manufacturing a relief material for seamless printing~~ according to ~~any one of claims~~ claim ~~[[1 to]]~~ 8, further comprising a carving step for fusion-removing ~~[[a]]~~ cured photosensitive resin from the cured layer by rotating the workpiece while linearly-moving a laser carving ~~means~~ device for carving the photosensitive resin cured layer on the outer periphery of the workpiece in the ~~axis-center~~ an axial direction of the workpiece and focusing one or more infrared laser beams applied from the laser carving ~~means~~ device on the photosensitive resin cured

layer in accordance with the control ~~[[by]]~~ of a digital image recording signal after either of the shaping step ~~[[and]]~~ or the first removing step.

10. (Currently amended) The method ~~for manufacturing a relief material for seamless printing~~ according to claim 9, further comprising~~[[:]]~~ a second removing step for removing ~~[[a]]~~ cured photosensitive resin ~~from the~~ cured layer in an area in which formation of ~~[[the]]~~ a relief image in the carving step is unnecessary to a desired thickness in parallel with or after the shaping step.

11. (Currently amended) The method ~~for manufacturing a relief material for seamless printing~~ according to claim 10, ~~characterized by laser carving wherein in the second removing step,~~ only a relief image forming area is laser carved by performing interlaced scanning for moving the laser carving ~~means~~ device at a high speed in ~~[[the]]~~ an image unnecessary area in the carving step when the photosensitive resin cured layer in the area in which formation of the relief image is unnecessary is removed to a desired thickness ~~in the second removing step~~.

12. (Currently amended) The method ~~for manufacturing a relief material for seamless printing~~ according to ~~any one of claims~~ claim 9 to 11, further comprising~~[[:]]~~ a cleaning step for cleaning the photosensitive resin cured layer ~~[[by]]~~ with a cleaning ~~means~~ device for spraying cleaning fluid having a pressure ~~between of~~ from 0.2 ~~[[and]]~~ to 30 MPa ~~{both included}~~ and a temperature ~~between of from~~ 40 ~~[[and]]~~ to 140°C ~~{both included}~~ onto the cured layer after any one of the carving step, removing step, and shaping step.

13. (Currently amended) The method ~~for manufacturing a relief material for seamless printing~~ according to ~~any one of claims~~ claim 9 to 12, further

comprising~~[[:]]~~ a post-exposing step for applying ultraviolet light to a relief image layer on the outer periphery of the workpiece while rotating the workpiece after either of the carving step ~~[[and]]~~ or cleaning step.

14. (Currently amended) The method ~~for manufacturing a relief material for seamless printing~~ according to claim 13, further comprising a surface modifying step for applying a surface modifying agent to the relief image layer for modifying the surface of ~~[[a]]~~ the relief image layer of the workpiece while rotating the workpiece ~~to the relief image layer~~ and then drying the agent.

15. (Currently amended) The method ~~for manufacturing a relief material for seamless printing~~ according to claim 14, ~~characterized by performing~~ wherein in the surface modifying step forcible heating and drying is performed while applying the surface modifying agent to the relief image layer ~~in the surface modifying step~~.

16-26. (Cancelled).

27. (New) The method according to claim 1, wherein the angle of inclination is an angle of from 15 to 75°.

28. (New) The method according o claim 1, wherein the applied thickness ranges from 0.5 to 3 mm.

29. (New) The method according to claim 1, wherein the resin supplying device includes a resin supplying nozzle.

30. (New) The method according to claim 29, wherein the linear mode is a mode in which the resin supplying nozzle supplies the liquid-state photosensitive resin to the resin receiving plate while the resin supplying nozzle linearly moves in an axial direction of the workpiece.

31, (New) The method according to claim 1, further comprising a carving step for fusion-removing cured photosensitive resin from the cured layer by rotating the workpiece while linearly-moving a laser carving device for carving the photosensitive resin cured layer on the outer periphery of the workpiece in an axial direction of the workpiece and focusing one or more infrared laser beams applied from the laser carving device on the photosensitive resin cured layer in accordance with the control of a digital image recording signal after either of a shaping step or a first removing step.